

Deed of Donation with Order no. 2/2025

concluded in accordance with the provisions of Section 2055 et seq. of Act No. 89/2012 Coll., the Civil Code, as amended.

1. PARTIES

CyberSecurity Hub, z.s. ("CSHub"), a registered institute existing under the laws of Czech Republic, having its registered office at Šumavská 416/15, 602 00 Brno, Czech Republic, company ID: 09705163
Delegated: Roman Čermák, M.Sc., MBA, Director
hereinafter referred to as the "**Donor**"

and

Masaryk University ("MU"), a public university existing under the laws of Czech Republic, having its registered office at Žerotínovo nám. 617/9/7, 601 77 Brno, Czech Republic, ID: 00216224
hereinafter referred to as the "**Donee**", enter into this deed of donation with the order (hereinafter also referred to as "**Deed**")

2. DECLARATION OF THE PARTIES

- 1.1 CSHub as the Donor declares he signed the *Agreement between NARLabs and CSHub* on May 17, 2024 to implement Advanced Chip Design Research Center (hereinafter also referred to as **ACDRC**) in the Czech Republic. Annex 1 to the Agreement between NARLabs and CSHub defines the **Working Plan** of ACDRC.
- 1.2 CSHub further declares he signed *Deed of Donation with Order* (hereinafter also referred to as **Primary Deed**) between Taipei Economic and Cultural Office, Prague (TECO) and CSHub on June 5, 2024, and therefore he shall receive a donation for the implementation of the ACDRC project.
- 1.3 The Donor and Donee (hereinafter also referred to as **Parties**) declare they signed the *Consortium Agreement on Implementation of Advanced Chip Design Research Center Between Cybersecurity Hub, Brno University of Technology, Czech Technical University, and Masaryk University* on December 12, 2024 including all of its Appendices (hereinafter also referred to as **Consortium Agreement**). The purpose of the Consortium Agreement is to establish an academic consortium (referred to herein as Consortium) on the Czech side to implement ACDRC.
- 1.4 According to Consortium Agreement, paragraph 2.5, a part of the funding received by CSHub on the Czech side shall be further distributed to consortium parties to finance the collaboration in the Consortium leading to implementation of the ACDRC.
- 1.5 This Deed is a partial implementation of the Consortium Agreement which also defines the terms and condition of this Deed.

3. SUBJECT OF THE DEED

- 3.1 With this Deed, the Donor will donate a financial amount of **CZK 4 500 000** (hereinafter referred to as the "**Donation**") to the Donee with an order for the partial implementation of the ACDRC project. The Donee accepts the Donation under this Deed on the terms and conditions set out in this the Primary Deed and this Deed. In case of discrepancy between Primary Deed and this Deed, the terms and conditions stated In the Primary Deed apply first.
- 3.2 The partial implementation is done in form of **Subprojects** under Work Package 3 as defined by the ACDRC Working Plan, a list of activities of the Donee and their incurred costs are described in Annex 1 to this Deed. These activities tasks from the ACDRC WP3 contribute to the overall goals of ACDRC.
- 3.3 The Donation defined in paragraph 2.1 of this Article shall be transferred to the Donee's bank account no.: **85636621/0100 (VS: 25322025)** in Komerční banka, a.s., after the conclusion of this Deed as one-time payment. The payment will be transferred without delays after this Deed comes into force and no later than 30 days after the signing of this Deed.
- 3.4 The Donor and the Donee agree that the conversion rate from USD to CZK is 22.559, based on the CNB conversion rate of June 7, 2024, when the donor received a donation from TECO.

4. TERMS AND CONDITIONS

A. General Terms

The Donee fulfills specific tasks from the ACDRC Working Plan and contributes to the overall goals of ACDRC. General Terms are defined in the Consortium Agreement unless specified otherwise in this Deed. General rules specifying the purpose of the Deed, but also non-eligible costs are defined in the Primary Deed (attached as Appendix 3 to the Consortium Agreement), under 4. Determination of the Order.

B. Coordinators:

The Parties will each designate a coordinator whose responsibility will be to develop formal agreements related to specific activities that may result from this Deed. Each Party designates the following people to facilitate and administer the fulfillment of this Deed:

- a. Donor: xxx
- b. Donee: xxx

C. Amendment:

This Deed and appendices may be amended as agreed upon by both Parties. Any amendments or modifications to this Deed shall be accepted by both Parties in writing, using an Amendment Document. Matters not included in the Deed, but directly related to it, may be addressed by an Amendment Document, and executed by both Parties. Any such agreement shall be appended to this Deed. This Deed is executed in electronic form with electronic signatures of both parties.

5. REGISTER OF CONTRACTS

By signing this Deed, both Parties confirm that they are aware that for the Donee, the Deed is subject to the obligation to publish it pursuant to Act. No. 340/2015 Coll., on the register of contracts, as amended. The Donor publishes this Deed.

IN WITNESS WHEREOF, both Parties have caused this Deed to be executed by their duly authorized representative.

Donor: CyberSecurity Hub, z.ú.	Donee: Masaryk University
02.06.2025	21.05.2025
(signed electronically) Roman Čermák, M.Sc., MBA Director	(signed electronically) prof. MUDr. Martin Bareš, Ph.D. rector

Annex 1: Description of the ACDRC Activities of the Donee according to 2.2

A. Activities according to 2.2

Title of the Subproject: Hands-on training on semiconductor device technology
Czech Consortium Partner (Donee): Masaryk University (Department of Condensed Matter Physics, Faculty of Science)

Project start date: 5/2025, end date: 12/2027

Principal Investigator: xxxxxxxxxxxxxxxxxxxxxxxx

Other staff: xx

Abstract (up to 200 words):

This educational subproject aims to promote courses on device preparation on wafers for students and trainees during various workshops and practical education activities. The practical work is carried out in the Department's clean room facility for semiconductor technology (class ISO 5), which is furnished with the laboratory equipment and production tools for wafer processing. The courses will allow participants to experience chip production techniques such as lithography, etching, sputtering or high-temperature processing, followed by structural and electrical studies of the produced layers and devices. The project will support the facility's operation and extension,, allowing it to reach a high standard of practical education courses on device and chip preparation for Czech as well as foreign course participants.

1.Detailed description (up to 2000 words):

This educational subproject, "Practical courses on semiconductor device preparation", which is a part of Work Package 3 of the ACDRC project, is focused on practical courses on preparation of semiconductor devices and chips on silicon wafers. The practical courses take place in the clean room facility for semiconductor technology (class ISO 5) at the Department of Condensed Matter Physics, Faculty of Science. The facility has been in operation since 2006, in close collaboration with company onsemi, particularly the ON Semiconductor Czech Republic in Rožnov pod Radhoštěm, which kindly provided some of the production tools. The laboratory is a unique university facility aimed mainly at educating students and trainees of the STEM studies. It has already been used not only by students of Masaryk University but also by students of other Czech universities. Their own experience in chip fabrication is a significant contribution to their studies, jobs or careers. The laboratory is equipped with standard "chip fab" tools for lithography, etching, sputtering or high-temperature processing, allowing for 4" wafer processing. Currently, the laboratory upgrade to larger wafer sizes is in preparation, in a close collaboration with onsemi.

This project aims to promote courses on device preparation on wafers for students, teachers, and other trainees (employees from other institutions or companies) during various workshops and practical education activities. The courses will allow participants to experience chip production techniques such as lithography, etching, sputtering or high-temperature processing (oxidation, annealing, doping), followed by structural and electrical studies of the produced layers and devices. This project will allow, in addition to current courses for students of Czech universities, to set up new courses for ACDRC workshop participants and for trainees in the chip or electronics development, production or testing-related companies.

This project will support the facility's operation and extension, allowing it to reach a high standard of practical education courses on device and chip preparation for Czech as well as foreign course participants. Because of the high clean class ISO 5 (required for all chip production facilities), the running, servicing and upgrade costs are quite high. The budget includes personal costs of the academic and

technical staff, scholarships for involved students, and servicing and device costs.

The milestones and deliverables include the preparation of course materials, evidence of the running performance of the laboratory, evidence of the laboratory upgrade for new technologies, workshop materials in English, and a minimal number of courses provided during the project duration.

2.Milestones and deliverables:

M1 – 12/2025 At least 1 practical course running during 2025 (ACDRC workshop or other).

M2 – 12/2026 Upgrade of the laboratory is available for trainees.

M3 – 12/2026 At least 2 practical courses running during 2026 (ACDRC workshop or other).

M4 – 12/2027 At least 2 practical courses running during 2027 (ACDRC workshop or other).

D1 – 12/2025 Progress report of the running project.

D2 – 12/2026 Progress report of the project activities.

D3 – 09/2027 Course materials in English.

D4 – 12/2027 Final report of the project.

3.Detailed budget table for all activities

Personal costs	2 260 000 CZK
Scholarship	60 000 CZK
Services (service costs of the air-conditioning system, demi water production, service of instrumentation, etc.)	840 000 CZK
Equipment (small instrumentation, clean chemicals, etc.)	440 000 CZK
Travel costs	0 CZK
Overheads	900 000 CZK
Total	4 500 000 CZK